

a molded body;  
a plurality of electronic parts sealed with the molded body; and  
a plurality of interconnections electrically connected to the electronic parts and sealed  
with the molded body,  
wherein the interconnections have a first exposed surface level with a first side of the  
molded body, and  
wherein the interconnections have a second exposed surface level with a second side  
of the molded body differing from the first side.

12. (Amended) The three-dimensional mounted assembly as defined in claim 11,  
the interconnections have third exposed surfaces, every side except the first and  
second sides of the molded body is level with one of the third exposed surfaces.

Please add new claim 21 as follows:

--21. (New) A three-dimensional mounted assembly comprising:  
a molded body, the molded body having a first side formed by a first mold, the  
molded body having a second side formed by a second mold;  
a plurality of electronic parts sealed with the molded body; and  
a plurality of interconnections electrically connected to the electronic parts and sealed  
with the molded body,  
wherein the interconnections have a first exposed surface formed by the first mold on  
a first side of the molded body, and  
wherein the interconnections have a second exposed surface formed by the second  
mold on a second side of the molded body differing from the first side.--

REMARKS

Claims 1-21 are pending. Claims 1-10 are withdrawn from consideration. By this  
amendment, the Title and Abstract are amended to reflect the invention; claims 13-16 are